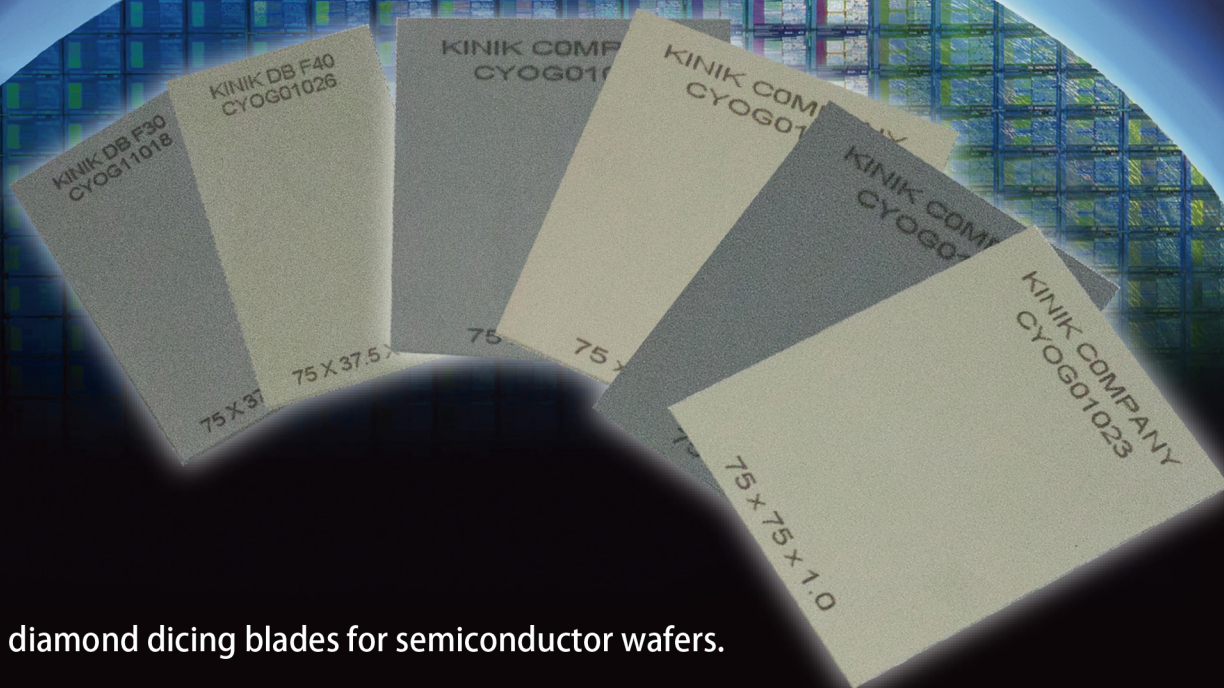
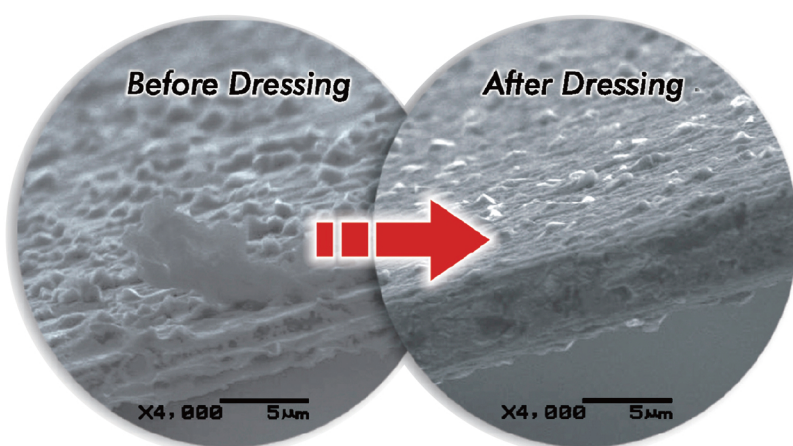




Dressing Board



To dress diamond dicing blades for semiconductor wafers.



To expose diamond grits of dicing blade by dressing board for sharper sawing and minimal chipper of as cut die edge.

Spec.	Dimension	Grit of Dicing blade
DB F30	75x75x1	D1800#~D3000#
	75x37.5x1	
DB F40	75x75x1	D3000#~D4000#
	75x37.5x1	
DB F405	75x75x1	D4000#~D4500#
	75x37.5x1	



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